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DATA SHEET

PART NO. : B-1005I

REV : A/0

CUSTOMER'S APPROVAL : \_\_\_\_\_

DCC : \_\_\_\_\_

DRAWING NO. : DS-17-18-0094G

DATE : 2018-05-15

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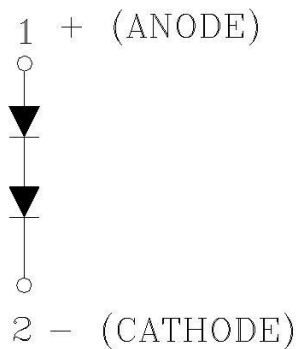
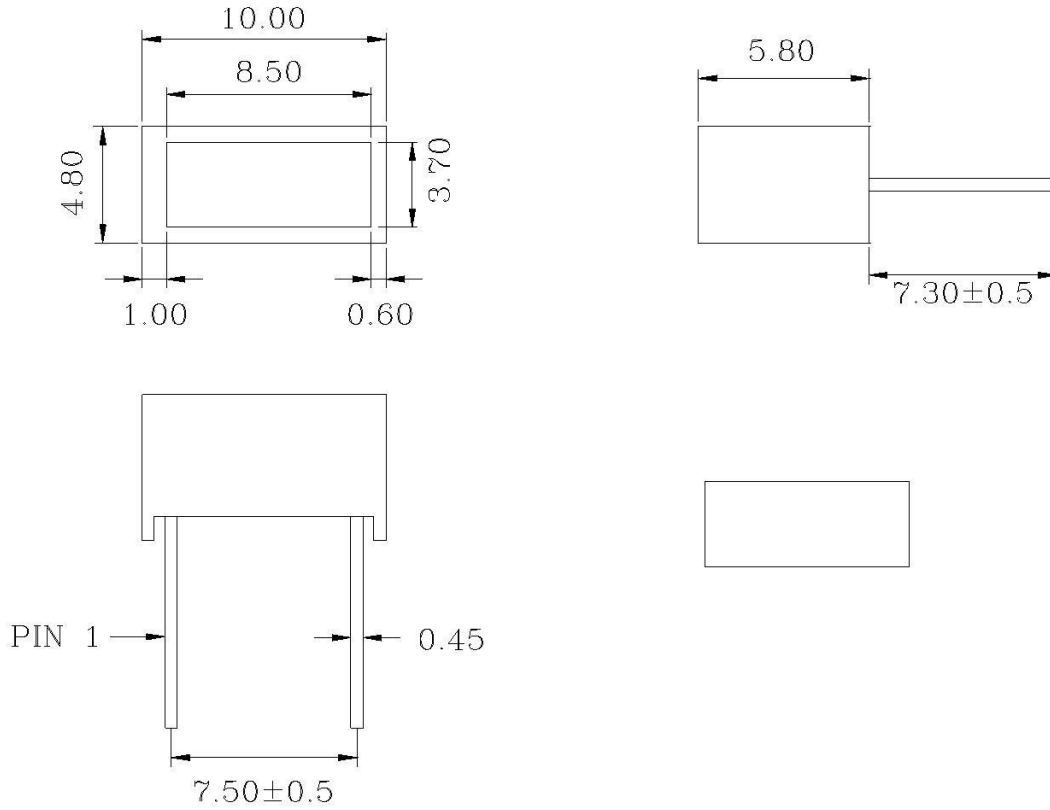


4.80 mm x 10.00mm SQUARE LIGHT BAR

B-1005I

REV:A / 0

PACKAGE DIMENSIONS



NOTES : 1. All dimensions are in millimeters. (inches)  
2. Tolerance is  $\pm 0.25(0.010)$  unless otherwise specified.



4.80 mm x 10.00mm SQUARE LIGHT BAR

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## FEATURES

4.80mm x 10.00mm SQUARE TRIANGLE LIGHT BAR  
 LOW POWER REQUIREMENT  
 CAN BE USED WITH PANEL AND LEGEND MOUNT  
 SUITABLE FOR MULTIPLEX OPERATION  
 EASY MOUNTING ON P.C.B  
 Pb FREE PRODUCTS  
 RED SEGMENTS

Raw Material : GaAlInP/GaAs

ABSOLUTE MAXIMUM RATING : ( Ta = 25°C )

SYMBOL	PARAMETER	SUPER RED	UNIT
PD	Power Dissipation Per Chip	60	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	30	mA
—	Derating Linear From 25°C Per Chip	0.4	mA/°C
Topr	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	

ELECTRO-OPTICAL CHARACTERISTICS : ( Ta = 25°C )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage , Per Chip	IF = 20mA		1.8	2.2	V
IR	Reverse Current , Per Chip	VR = 5V			100	μA
λP	Peak Emission Wavelength	IF = 20mA		660		nm
λD	Dominant Wavelength	IF = 20mA		640		nm
Δλ	Spectral Line Half-Width	IF = 20mA		20		nm
IV	Luminous Intensity Per Bar	IF = 10mA	1.6	4.0		mcd

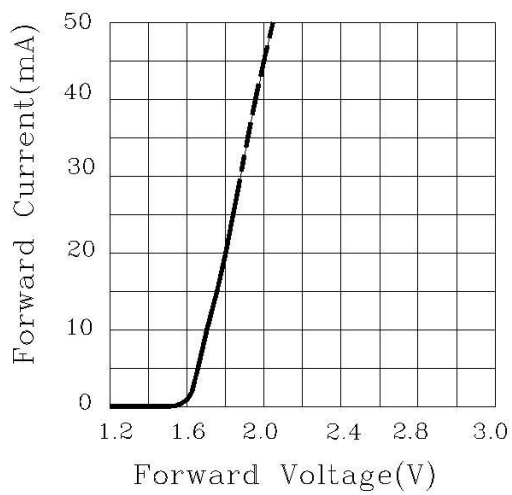


4.80 mm x 10.00mm SQUARE LIGHT BAR

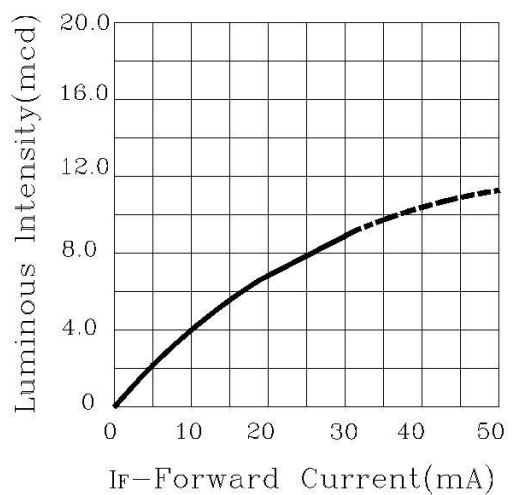
B-1005I

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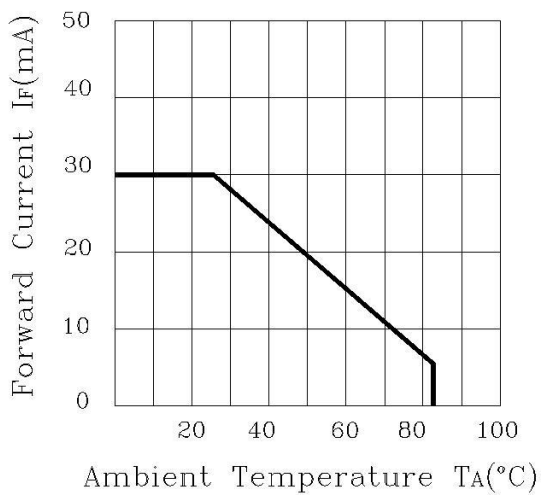
FORWARD CURRENT Vs. FORWARD VOLTAGE



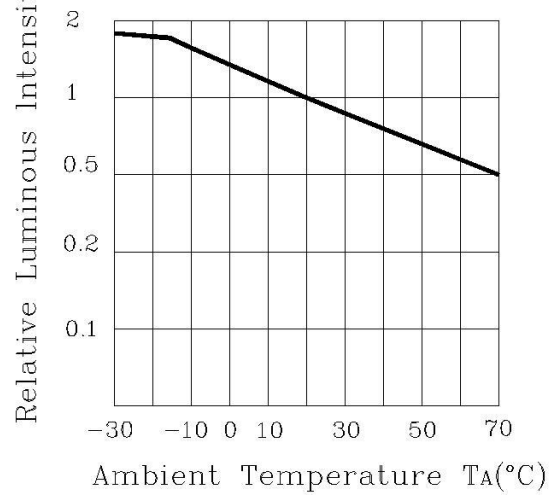
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE





4.80 mm x 10.00mm SQUARE LIGHT BAR

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**SOLDERING**

METHOD	SOLDERING CONDITIONS	REMARK
DIP SOLDERING	Bath temperature: 250 max Immersion time: with 3sec	Solder no closer than 2mm from the base of the package Using soldering flux," RESIN FLUX" is recommended.
		During soldering, take care Temperature at tip of iron: 360°C or not to press the tip lower of iron against the smaller Soldering iron: 30W or smaller

**SOLDERING**

IRON

prevent heat from being

Soldering time: within 3 sec.

(To

transferred directly to the PIN.)

- 1) When soldering the PIN of Display in a jig that the package is fixed with a panel (See flg.1), be careful not to stress the PIN with iron tip. When soldering Display in a condition that the package is fixed with a panel, be careful not to cling and stress the surface of Display on the panel to avoid damaging the Display.

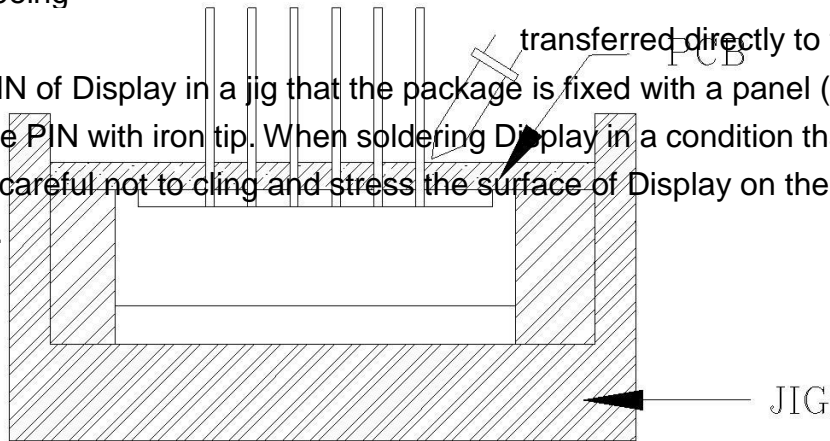


Fig.1

alloyed solution is tin 95.5: copper 3.5: silver 0.5 by percentage. The time of tinning is constantly 3 seconds.

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